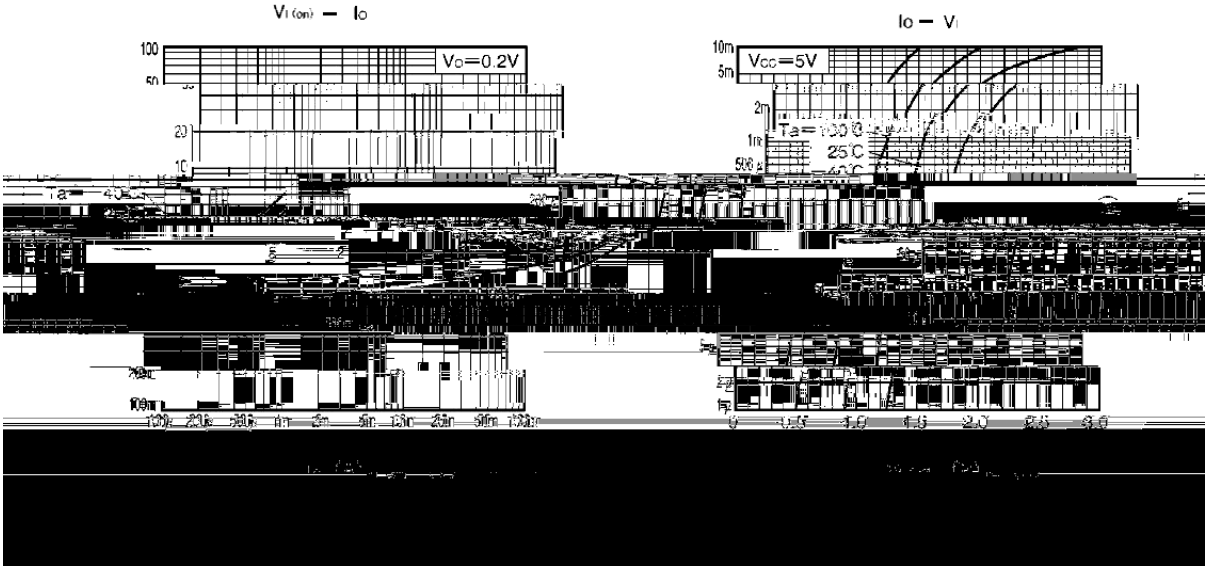
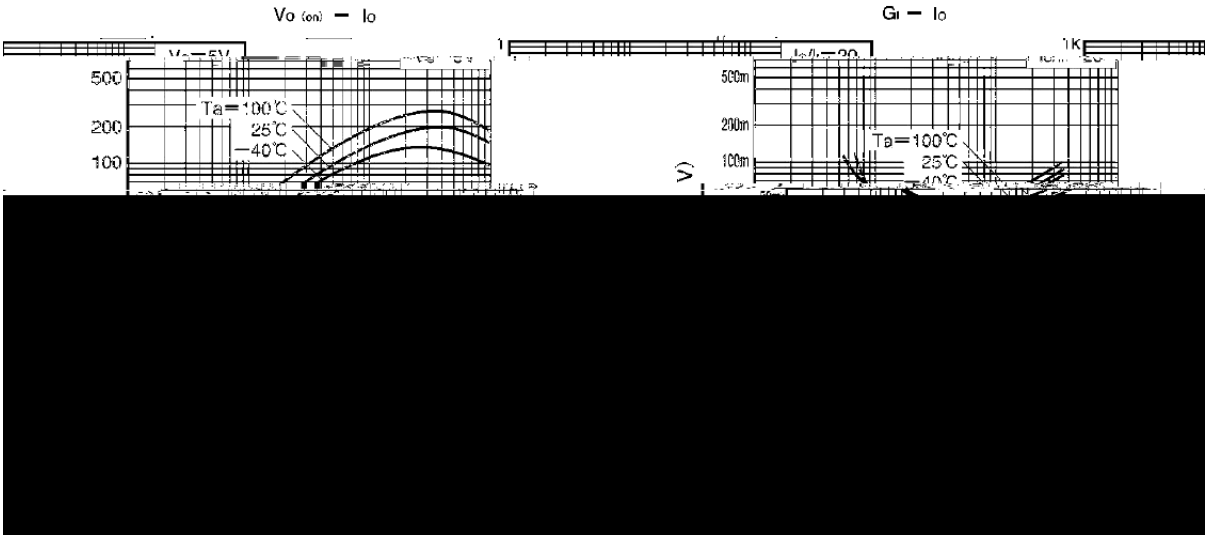
SOT-23	NPN	Silicon NPN Digital transistor in a SOT-23 Plastic Package.

Parameter	Symbol	Rating	Unit
Output Voltage	V_{CC}	50	V
Input Voltage	V_{IN}	40	V
		-10	V
Output Current	I_C	100	mA
	I_O	30	mA
Power Dissipation	P_C	200	mW
Junction Temperature	T_j	150	
Storage Temperature Range	T_{stg}	-55 150	

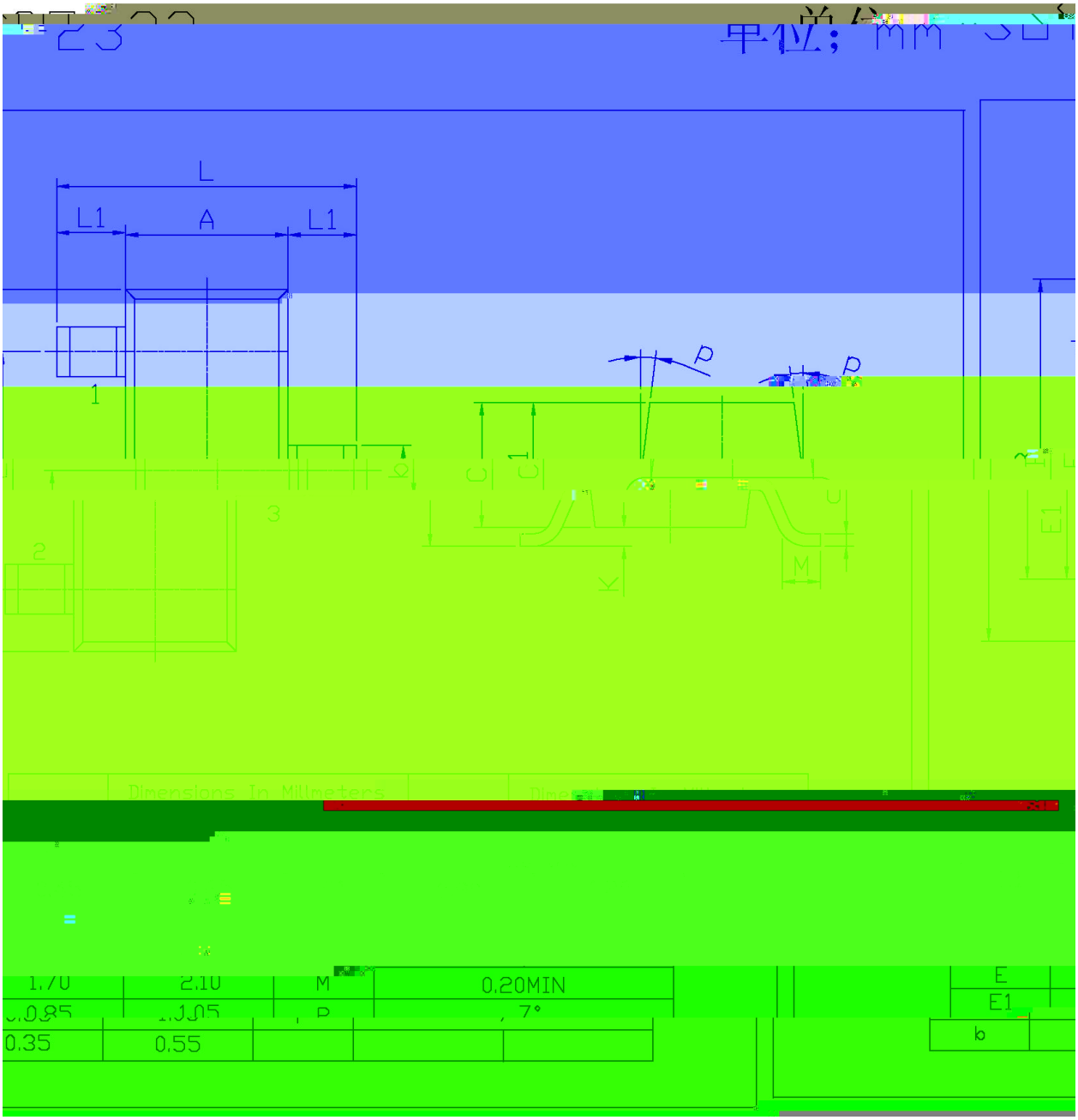
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Input Voltage(OFF)	$V_{I(off)}$	v_{CC}=5.0V I_O=100 A			0.5	V
Input Voltage(ON)	$V_{I(on)}$	V_O=0.2V I_O=5.0mA	3.0			V
Output Voltage	$V_{O(on)}$	I_O=10mA I_I=0.5mA		0.1	0.3	V
Input Current	I_I	V_I=5.0V			0.36	mA
Output Cut-off Current	$I_{O(off)}$	V_{CC}=50V V_I=0V			0.5	A
DC Current Gain	G_I	V_O=5.0V I_O=5.0mA	56			
Transition Frequency	f_T	V_{CE}=10V I_C=5.0mA f=100MHz		250		MHz
Resistance1	R_1		15.4	22	28.6	K
Resistance Ratio	$R_2$2					

/ Electrical Characteristic Curve

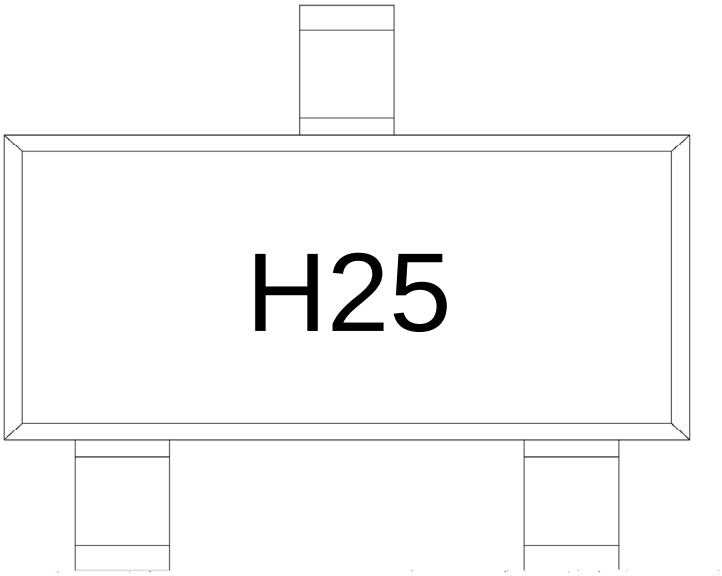




/ Package Dimensions



/ Marking Instructions



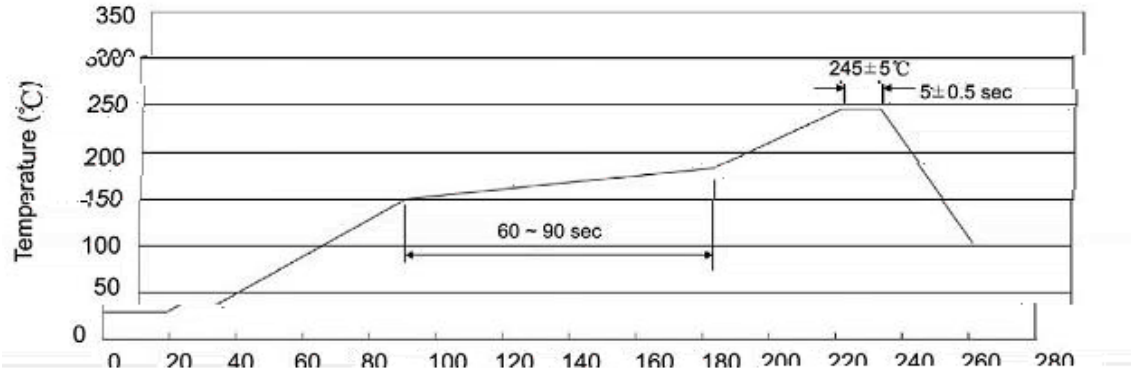
H

25

Note:

H	Company Code
25	Product Type Code

( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



			Note:
1	150 180	60 90sec;	1.Preheating:150~180 , Time:60~90sec.
2	245±5	5±0.5sec;	2.Peak Temp.:245±5 , Duration:5±0.5sec.
3	2 10 /sec.		3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

260±5	10±1 sec.	Temp.:260±5	Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units					Dimension		(unit mm^3)
	Units/Reel /	Reels/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Reel	Inner Box	Outer Box
SOT-23	3,000	10	30,000	6	180,000	7 ×8	180×120×180	390×385×205

/ Notices